Taipei, Taiwan

2027 IEEE ISPSD

2027 IEEE International Symposium on Power Semiconductor Devices and ICs



13-17, June

TICC,Taipei, Taiwan

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Sponsorship and Exhibition Prospectus

The 39th International Symposium on Power Semiconductor Devices and ICs (ISPSD 2027) will be held from June 13 to 17, 2027, at the Taipei International Convention Center (TICC) in Taipei, Taiwan, bringing together leading experts from academia and industry in the field of power semiconductor devices and power integrated circuits. As the premier international conference in this field, ISPSD provides a highly focused platform for the presentation and discussion of cutting-edge technologies and applications.

A dedicated exhibition will run alongside the technical symposium over two and a half days, offering exhibitors a direct platform to present their latest technologies, solutions, and innovations to a highly specialized audience in the power semiconductor field. Sponsors and exhibitors will benefit from multi-channel visibility, with branding featured across key conference touchpoints such as the official website, conference materials, on-site displays, and more. This event provides a valuable channel to enhance industry visibility and engage with potential partners and customers from around the world.

ISPSD 2027 offers an exceptional platform to enhance brand presence and strengthen positioning within the global power semiconductor community. We sincerely invite your support and participation in making ISPSD 2027 in Taipei a highly successful and impactful event.

Tom J.-L. Tsai
General Chair, ISPSD 2027

Lee, Sang Gi
TPC Chair, ISPSD 2027

Ian Y.-J., Chan
Vice General Chair, ISPSD 2027

Chih-Fang Huang
TPC Co-Chair, ISPSD 2027

For any inquiries, please contact the Secretariat of ISPSD 2027
Email: secretariat@ispsd2027.com

Symposium Outline

Symposium Name	The 39th International Symposium on Power Semiconductor Devices and ICs (ISPSD 2027)
Dates	June 13 (Sun.) - June 17 (Thu.), 2027
Venue	Taipei International Convention Center (TICC) No. 1, Section 5, Xinyi Road, Xinyi District, Taipei City, Taiwan
Expected Number of Participants	400
Expected Number of Presentations	250 (including oral and poster presentations)
General Chair Vice General Chair	Tom J.-L. Tsai (TSMC) Ian Y.-J., Chan (Cyntec)
Technical Program Chair Technical Program Co-Chair	Sang Gi Lee (DB HiTek) Chih-Fang Huang (EE Dept., NTHU)
Sponsor	Institute of Electrical and Electronics Engineers
Co-Sponsor	The IEEE Electron Devices Society (EDS) The IEEE Power Electronics Society (PELS)
Main Categories of Interest	High Voltage Devices (HV) Low Voltage Devices and Power IC Device Technology (LVT) Power IC Design (ICD) GaN and Compound Materials SiC and Other Materials (SiC) Module and Packaging Technologies (PK)
Secretariat	secretariat@ispsd2027.org
Official website	https://ispsd2027.com/

Organizing Committee

General Chair	Tom J.-L. Tsai, TSMC
Vice General Chair & Treasure	Ian Y.-J., Chan, Cyntec
Technical Program Chair	Sang Gi Lee, DB HiTek
Technical Program Co-Chair **Publicity Co-Chair**	Chih-Fang Huang, EE Dept., NTHU
Short Course Chair **Publication Co-Chair**	Roy King-Yuen Wong, EE Dept., NTHU
Publicity Co-Chair	Robert Wei-Chung Lo, Dep. GM, ITRI Electronics & Optoelectronics Lab
Local Arrangement	Kung-Yen Lee, ESOE Dept., NTU
Exhibitor Chair	CT Yen, Fast SiC Semiconductor
Publication Co-Chair	Shu Yang, USTC

Premier Partnership Opportunities

PREMIER PARTNERSHIP

Premier partners, e.g. Diamond, Platinum, Gold, Silver, and Bronze partners enjoy exclusive benefits, including wide acknowledgement and priority to select certain partnership items, and will enjoy exclusive privileges listed below at no extra cost.

CATEGORIES OF PREMIER PARTNERSHIP

Category	Price (NTD)	Number of Availability
Platinum	700,000	2
Gold	400,000	5
Silver	200,000	10
Exhibitor	150,000	17

ALL SPONSORSHIP OPPORTUNITIES ARE AVAILABLE AND ALLOCATED ON A FIRST-COME, FIRST-SERVED BASIS

Sponsorship Packages

	Category	Platinum	Gold	Silver	Exhibitor
	Fee (NTD)	700,000	400,000	200,000	150,000
Logo Visibility	Official Website	V	V	V	V
	Agenda Board	V	V	V	V
	Program Book	V	V	V	V
	Spiritual Fortress	V	V	V	V
	Logo on Lanyards	V			
Ad	Promotional Video during Breaks or before/after Oral Sessions (Maximum 3 min.; Provided by Sponsor)	V	V		
	Advertisement in Program Book (Full-Page, A5 size; E-copy Provided by Sponsor)	Inside Front Cover / Back Cover			
	Advertisement in Program Book (Full-Page, A5 size; E-copy Provided by Sponsor)		One Inner Page	One Inner Page	
	Insertion in the Congress Bag (Maximum of Two Items; Provided by Sponsor)	V	V	V	
Access	Complimentary Congress Registration and Banquet Participation	3	2	1	1
	Exhibitor Badge	4	2	2	2
Exhib.	Exhibition Booth	1	* Booth special rate : 50,000 for 3M*2M booth	** Booth special rate : 100,000 for 3M*2M booth	Yes
	Booth Size	3M*2M	NA	NA	3M*2M

*Sponsor packages Gold and Silver do NOT include a booth. Please also register as an Exhibitor if you need a booth. *ALL SPONSORSHIP OPPORTUNITIES ARE AVAILABLE AND ALLOCATED ON A FIRST-COME, FIRST-SERVED BASIS*

Additional Sponsorship Opportunities

Cat.	Option	Fee (NTD)
Ad (provided by sponsor)	Full-Page Advertisement in Program Book (Inner Page)	**25,000**
	Back Cover Advertisement in Program Book (Exclusive)	**100,000**
	Insertion of One Item in the Congress Bag	**100,000**
	Single-Sided Banner above Main Escalator (North or South Side)	**300,000**
	One-Time E-Marketing Blast to Registered Participants prior to the Congress	**40,000**
	Promotional Video during Breaks or before/after Oral Sessions (Maximum 3 min.)	**50,000**
Logo Visibility	Congress Bag	**150,000**
	Welcome Reception	**350,000**
	Lunch	**200,000**
	Coffee Break	**100,000**
	Speaker Ready Room	**100,000**
	Poster Area	**100,000**

*Pricing includes tax.

Exhibition Outline

Venue	Taipei International Convention Center (TICC) No. 1, Section 5, Xinyi Road, Xinyi District, Taipei City, Taiwan	
Dates	Setting up	13 June (Sun.) 08:00 – 17:30
	Opening hours	14 June (Mon.) 12:00 – 17:30 15 June (Tue.) 08:00 – 17:30 16 June (Wed.) 08:00 – 12:00
	Dismantle	16 June (Thu.) 12:00 – 17:30
	***The schedule is subject to change. The final schedule will be shared in due course.**	
Exhibition Area	South Corridor & South Lounge Area, 1st floor, Taipei International Convention Center (TICC)	
Exhibition Fee and Benefits	Please refer to the *Sponsorship Packages* page for details. Booths are available on a first-come, first-served basis.	

*The organizer reserves the right to change the time and venue without prior notice.

Booth Specifications

SHELL SCHEME

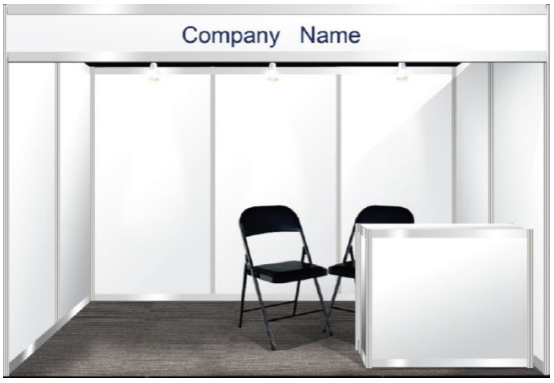
The booth type will be assigned based on your selected Sponsorship Package and cannot be changed.

Size	Price (NTD)
Standard booth: 3 m x 2 m	*150,000*

Standard Booth

Besides the basic entitlements, Shell Scheme Booths
include:

- Shell scheme frame, basic lighting
- Fascia panel with standard lettering
- 2 chairs, 1 table
- Socket (110V/5A)



EXHIBITORS' TECHNICAL MANUAL

An Exhibitors' Technical Manual outlining all technical aspects of exhibiting will be circulated 3 months prior to the Conference. It will include the following:

- Technical details about the Venue
- Final exhibition details and information
- Contractor details
- Services available to exhibitors and order forms

EXHIBITION TERMS & CONDITIONS

The Terms and Conditions of exhibiting are included in this Prospectus. Signing of the **ISPSD 2027** APPLICATION FORM indicates acceptance of these Terms and Conditions. The **ISPSD 2027** APPLICATION FORM will be held as a valid liable contract, by which both parties will be bound.

Important Notices for Exhibitors

The Exhibitor Technical Manual, together with order forms for optional items and services, will be provided to exhibitors in due course. All exhibitors are required to comply with the regulations set by the Organizer and the venue.

Exhibition Terms & Conditions

The Organizing Committee reserves the right to amend the floor plan, or any part thereof, at any time. In the event of unforeseen circumstances, the Organizer also reserves the right to change the conference venue, dates, or format.

Booth Allocation

Booths are allocated on a first-come, first-served basis, subject to exhibitor preference and availability. Exhibitors are not permitted to transfer, sublet, or exchange all or part of their allocated booth without prior approval from the Organizer.

Venue Management & Liability

The Organizer and the venue shall not be held responsible for any accidents, theft, loss, or personal injury occurring within the exhibition area due to natural disasters or other force majeure events.

Exhibitor Badges & Fees

Each booth includes two exhibitor badges. Additional exhibitor badges may be purchased at NT$3,000 (approximately US$100) per person. This fee includes access to coffee breaks and the Welcome Reception.

Promotional Activities

- All demonstrations and promotional activities must be conducted within the boundaries of the assigned booth. Distribution or display of promotional materials outside the booth is not permitted.
- Sound equipment must be kept at a reasonable volume and directed inward so as not to disturb neighboring exhibitors. The Congress Secretariat reserves the right to request the immediate cessation of any activity, noise, or music deemed inappropriate or disruptive. Further details will be provided in the Exhibitor Technical Manual.

How to Apply and Future Procedure

How to Apply

Please fill in the attached ***Application Form*** and send it by e-mail to the Conference Secretariat at secretariat@ispsd2027.com by **December 23, 2026 (UTC+8)**.

Payment Method

Payment should be made by **telegraphic transfer (TT)** to the following:

Beneficiary's Name	GIS Group Global Co. LTD 集思國際會議顧問有限公司
Bank Name	E.SUN Commercial Bank, Ltd., Taipei, Taiwan 玉山商業銀行股份有限公司 信義分行
SWIFT Code	ESUNTWTPXXX
Account No.	1229-940-002628
Bank TEL.	+886 2 8789-1313
Important Note	The bank account below is designated for payments in **New Taiwan Dollars (TWD) only.** If you wish to make payment in **US Dollars (USD)**, please contact the **ISPSD 2027 Secretariat** for the appropriate USD remittance details.

All bank charges (including inbound and/or outbound administration fees) are to be borne by the remitter. When making the transaction, kindly ensure to select "OUR" as the payment option. Kindly provide this instruction to your bank during the remittance/tele-transfer of your payment.

Cancellation Policy

- No cancellations will be accepted after payment. However, if cancellation is caused by unavoidable reasons, please write to the Secretariat at secretariat@ispsd2027.com for the circumstances, and the organizer has the right to accept/decline the cancellation/withdrawal requests. If cancellation is approved, you may be charged for expenses incurred at that time.
- The exhibition period and venue may be changed due to unavoidable circumstances. In principle, applications cannot be cancelled due to such changes. In the event of a postponement, applications that have already been submitted will, in principle, be moved to the postponed date. No compensation will be provided for damages caused by these changes.

ISPSD 2027 APPLICATION FORM

October 2026 Version

Please return the application form to the Conference Secretariat:

GIS GROUP GLOBAL CO. Ltd.

Conference Secretariat Mr. Claud Chen

Conference SecretariatContact No. +886-2-87805688 #170

Contact Email sponsorship@ispsd2027.com

Company Name			
Contact Person		**Position**	
Contact Email			
Contact No.			
Mobile No.			
Company Address			
Company Website			

Exhibition spaces will be allocated based on each sponsor's total sponsorship amount, following a first-come, first-served principle.

Please choose from the following items		Unit Price	Unit	Total
Premier Sponsorship				
1	Platinum	NTD. 700,000		
2	Gold	NTD. 400,000		
3	Silver	NTD. 200,000		
4	Exhibitor	NTD. 150,000		

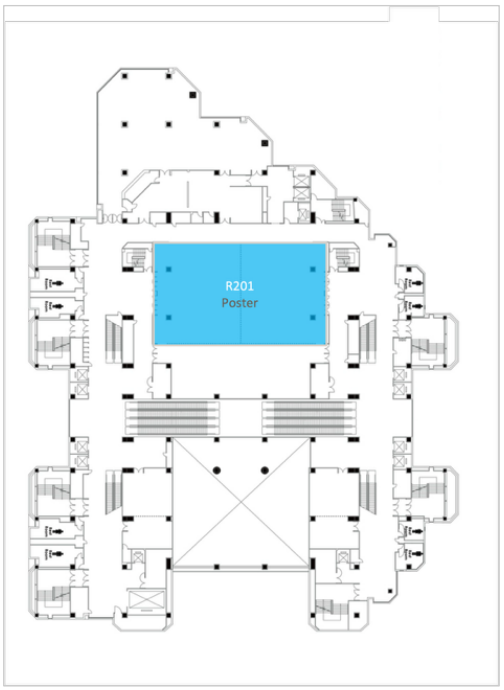
Cat.	Option	Unit	Total
Ad (provided by sponsor)	Full-Page Advertisement in Program Book (Inner Page)		
	Back Cover Advertisement in Program Book (Exclusive)		
	Insertion of One Item in the Congress Bag		
	Single-Sided Banner above Main Escalator (North or South Side)		
	One-Time E-Marketing Blast to Registered Participants prior to the Congress		
	Promotional Video during Breaks or before/after Oral Sessions (Maximum 3 min.)		
Logo Visibility	Congress Bag		
	Welcome Reception		
	Lunch		
	Coffee Break		
	Speaker Ready Room		
	Poster Area		

Floor Plan

1F, TICC



2F, TICC



*The floor plan is subject to change.